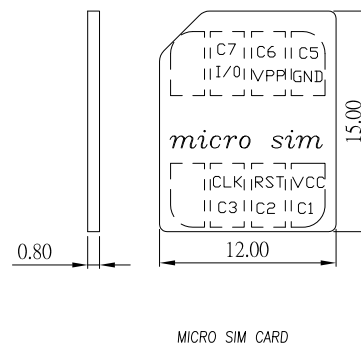
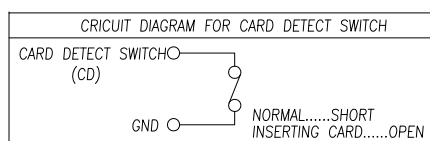
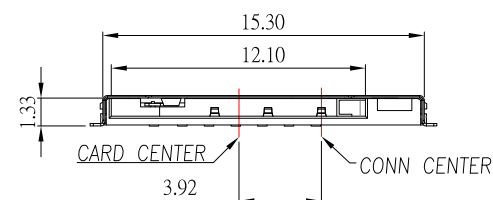
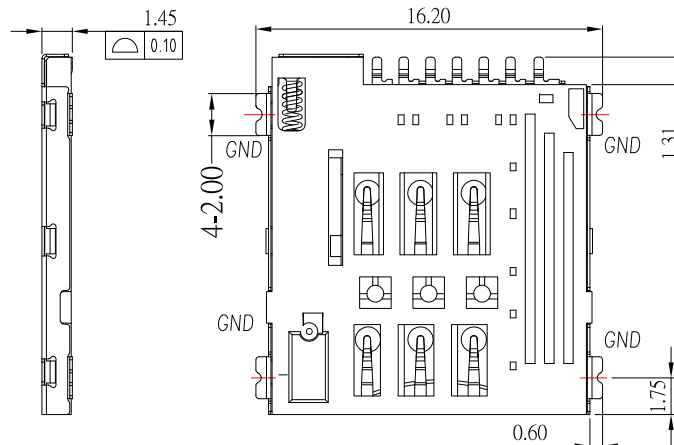
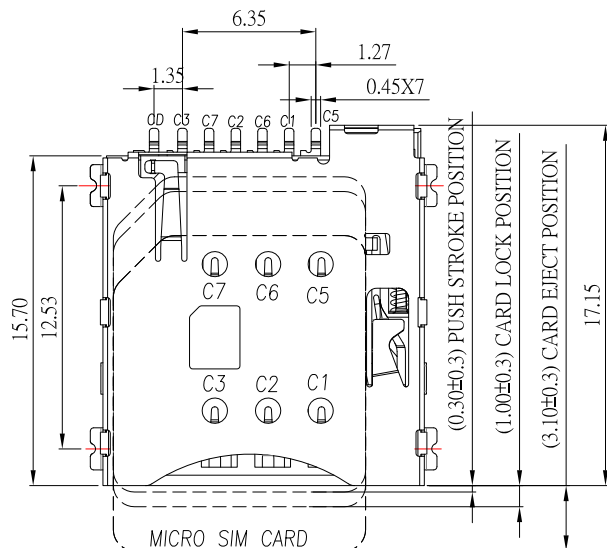
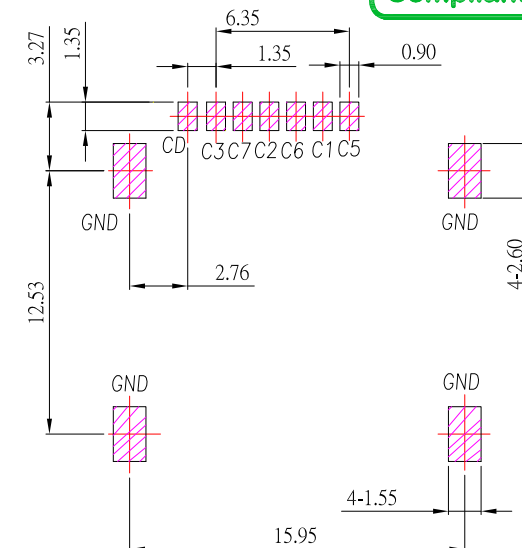




SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



PCB LAYOYT

Material:

- 1.Housing: LCP
- 2.Contact: Copper Alloy
- 3.Shell: SUS

Finish:

- 1.Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall
- 2.Shell: Nickel under Plated surface laye



建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 10/28/20
DATE: 10/28/20
DATE: 10/28/20

MATL	TITLE	CONNECTOR
FINISH	MODLE	MICRO SIM CARD PUSH PUSH 7PIN 1.45H 带CD PIN(防呆型)
SCALE	DWG NO.	MSIM-S3071-A1-S304
SHEET NO.	PART NO.	MSIM-S3071-A1-S304

SIZE
A4
VER
R3

ITEM NO	DESCRIPTION	DRAWN	DATE
3	更新樣式	Jack	102820
2	更新尺寸	Jack	101518
1	更新樣式	Jack	101218